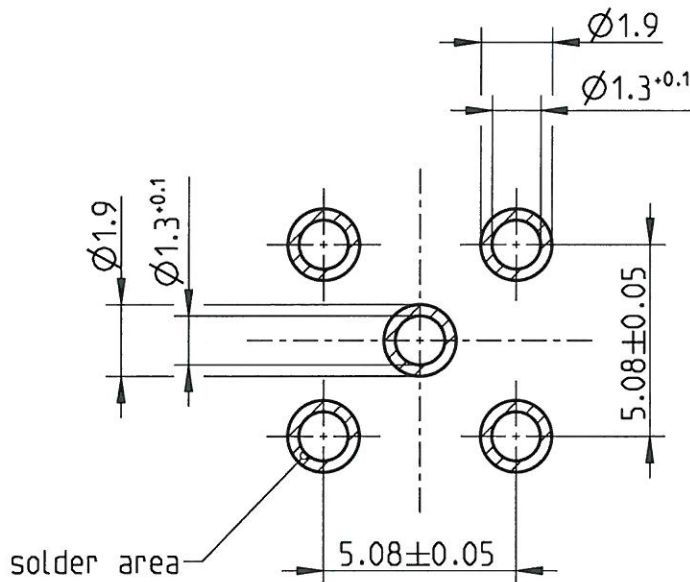


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Leiterplatten-Layout  
PCB layout  
B 30



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A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.

Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector.

In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Fernjahr: TCC\_F8\_05\_PC\_A4\_Linienleit  
Platz: 15-Proz-confirg/3ahnen  
Datei: A\_UMZEE\_TL\_C081.RH  
Version: 11

ISO-Projektion  
Methode E  
-METRIC-

<b>Rosenberger</b> Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER				general tolerance <b>ISO 2768 RN 006-01</b> m-H dimensions <0,5 and symmetry		scale: 5:1	weight[g]: surface[mm <sup>2</sup> ]:
				date drawn 15.02.2001 A_Nobis check. 20.3.06 WJ appr. 30.03.06 Wambach		material:	
				name date drawn 15.02.2001 A_Nobis check. 20.3.06 WJ appr. 30.03.06 Wambach		title: <b>Leiterplatten-Layout PCB layout</b>	
g00 06-0194 S_Krautenbac 24.03.2006 f00 04-0709 A_Nobis 22.11.2004 e00 02-0124 A_Nobis 01.10.2003 d00 01-0425 A_Nobis 06.09.2001 c00 01-0266 V_Spitzauer 13.06.2001				dimensioning incl. finish		drawing-no.: <b>MB_30</b>	
rev. change-no name date				distribu- tion to: FE AZ QSM RMT . X . . . .		sheet: 1 of: 1	
				remarks: .			